

Features

- ESD Protected Up To 2KV (HBM)
- Trench LV MOSFET Technology
- Moisture Sensitivity Level 1
- Halogen Free. "Green" Device (Note 1)
- Epoxy Meets UL 94 V-0 Flammability Rating
- Lead Free Finish/RoHS Compliant ("P" Suffix Designates RoHS Compliant. See Ordering Information)

Maximum Ratings

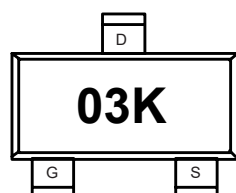
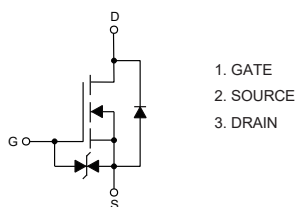
- Operating Junction Temperature Range: -55°C to +150°C
- Storage Temperature Range: -55°C to +150°C
- Thermal Resistance: 125°C/W Junction to Ambient^(Note2)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	±12	V
Continuous Drain Current	I_D	0.8	A
		0.51	
Pulsed Drain Current ^(Note 3)	I_{DM}	3.2	A
Total Power Dissipation ^(Note 4)	P_D	1	W

Note:

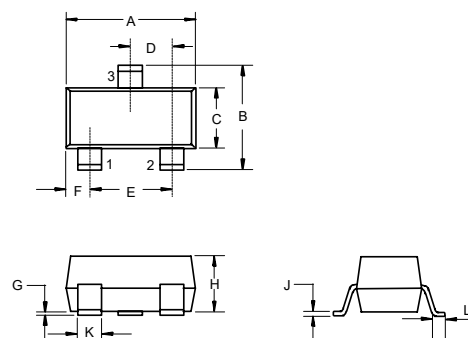
1. Halogen free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
2. The value of $R_{\theta JA}$ is measured with the device mounted on the minimum recommended pad size, in a still air environment with $T_A = 25^\circ\text{C}$.
3. Repetitive rating; pulse width limited by max. junction temperature.
4. P_D is based on max. junction temperature, using junction-ambient thermal resistance.

Internal Structure and Marking Code



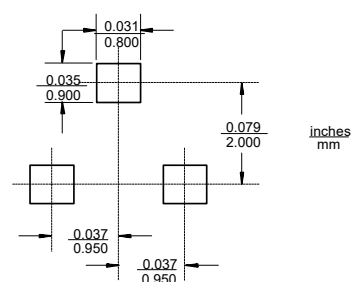
N-Channel MOSFET

SOT-23



DIM	INCHES		MM		NOTE
	MIN	MAX	MIN	MAX	
A	0.110	0.120	2.80	3.04	
B	0.083	0.104	2.10	2.64	
C	0.047	0.055	1.20	1.40	
D	0.034	0.041	0.85	1.05	
E	0.067	0.083	1.70	2.10	
F	0.018	0.024	0.45	0.60	
G	0.0004	0.006	0.01	0.15	
H	0.035	0.043	0.90	1.10	
J	0.003	0.007	0.08	0.18	
K	0.012	0.020	0.30	0.51	
L	0.007	0.020	0.20	0.50	

Suggested Solder Pad Layout



Electrical Characteristics @ 25°C (Unless Otherwise Specified)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} =0V, I _D =250μA	30			V
Gate-Source Leakage Current	I _{GSS}	V _{DS} =0V, V _{GS} =±12V			±10	μA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =24V, V _{GS} =0V			1	μA
Gate-Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	0.6	1.0	1.3	V
Drain-Source On-Resistance	R _{DS(on)}	V _{GS} =4.5V, I _D =0.5A		340	510	mΩ
		V _{GS} =2.5V, I _D =0.3A		435	660	
Forward Tranconductance	g _{FS}	V _{DS} =5V, I _D =0.8A		1.8		S
Gate Resistance	R _g	f=1 MHz, Open drain		197		Ω
Diode Characteristics						
Continuous Body Diode Current	I _S				0.8	A
Diode Forward Voltage	V _{SD}	V _{GS} =0V, I _S =0.5A			1.2	V
Reverse Recovery Time	t _{rr}	I _F =0.5A, di/dt=100A/μs		5.9		ns
Reverse Recovery Charge	Q _{rr}			2		nC
Dynamic Characteristics						
Input Capacitance	C _{iss}	V _{DS} =15V, V _{GS} =0V, f=1MHz		34.6		pF
Output Capacitance	C _{oss}			6.2		
Reverse Transfer Capacitance	C _{rss}			3.9		
Total Gate Charge	Q _g	V _{DS} =15V, V _{GS} =4.5V, I _D =0.5A		0.64		nC
Gate-Source Charge	Q _{gs}			0.09		
Gate-Drain Charge	Q _{gd}			0.17		
Turn-On Delay Time	t _{d(on)}	V _{DD} =15V, V _{GS} =4.5V , R _G =3Ω, I _D =0.5A		8.2		ns
Turn-On Rise Time	t _r			23.3		
Turn-Off Delay Time	t _{d(off)}			34.2		
Turn-Off Fall Time	t _f			31.5		

Curve Characteristics

Fig.1 - Typical Output Characteristics

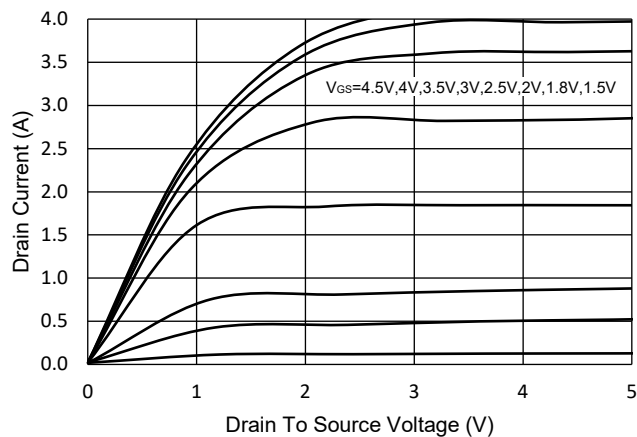


Fig.2 - Transfer Characteristic

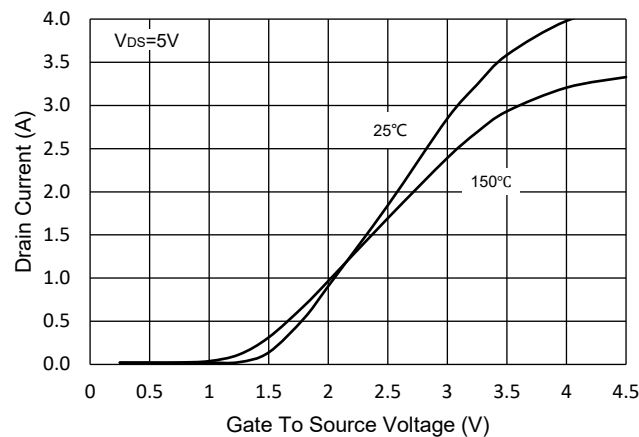


Fig.3 - $R_{DS(ON)}$ - V_{GS}

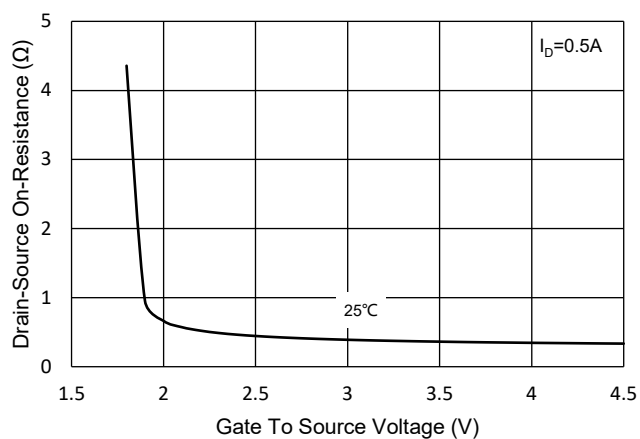


Fig.4 - $R_{DS(ON)}$ - I_D

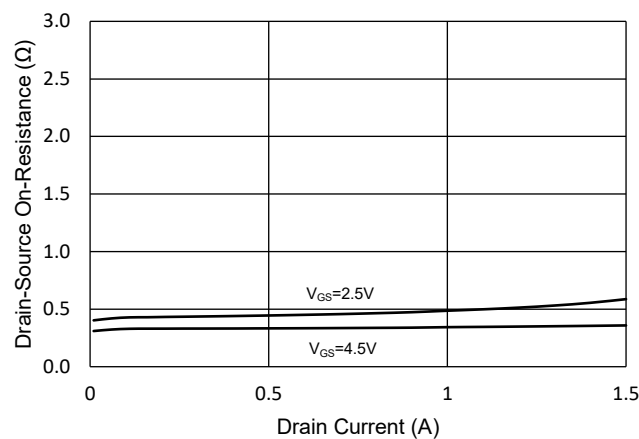


Fig.5 - Capacitance Characteristics

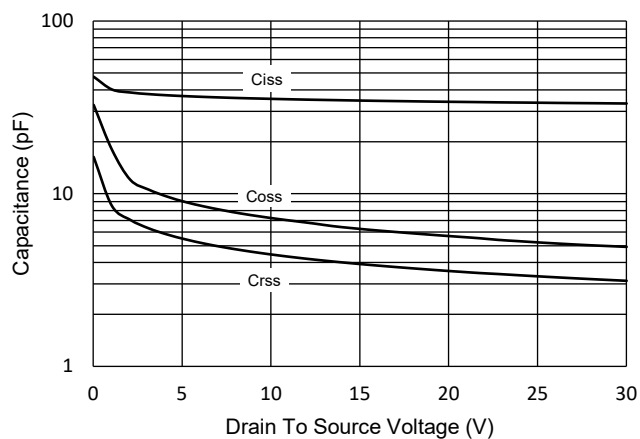
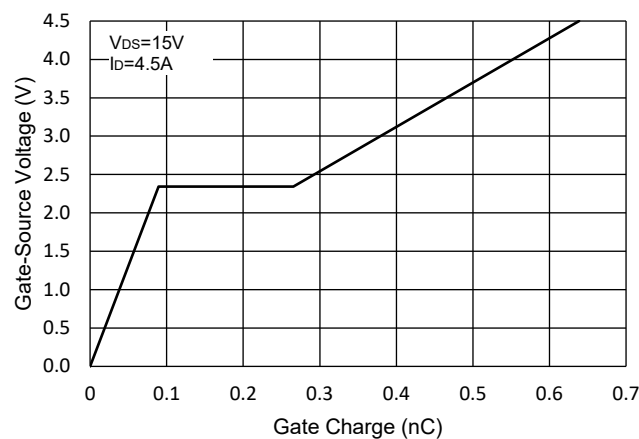


Fig.6 - Gate Charge



Curve Characteristics

Fig.7 - Normalized Threshold Voltage

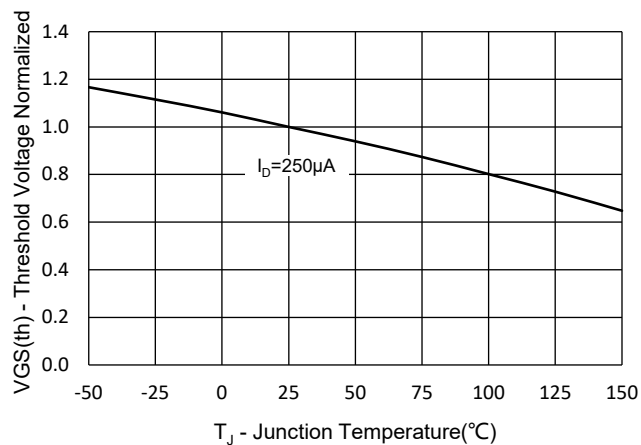


Fig.8 - Normalized On Resistance Characteristics

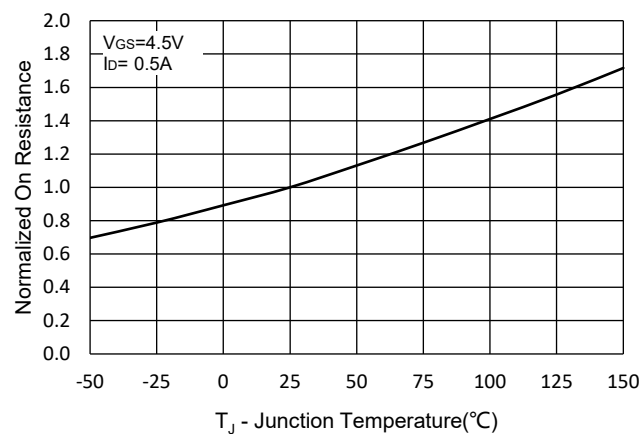


Fig.9 - $I_S - V_{SD}$

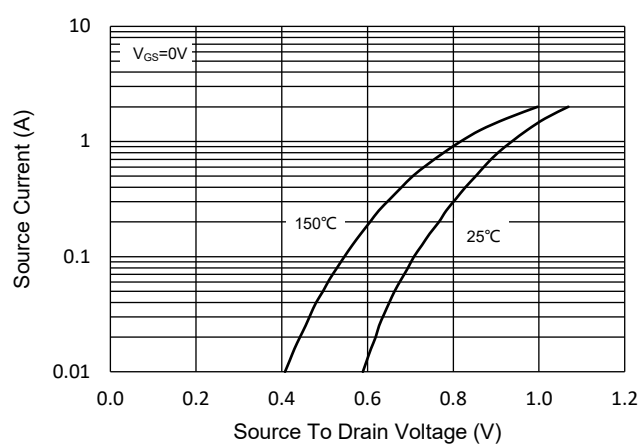


Fig.10 - Drain Current

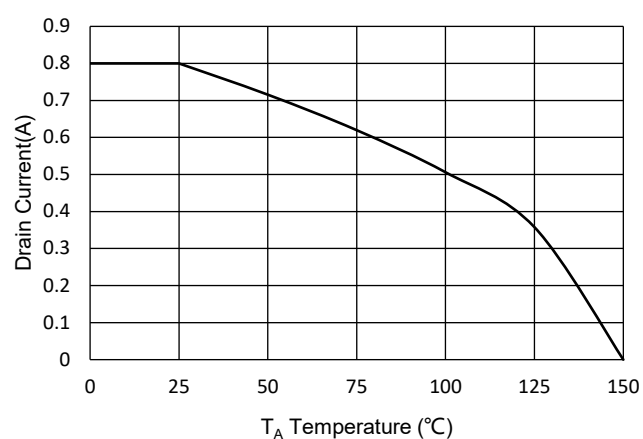
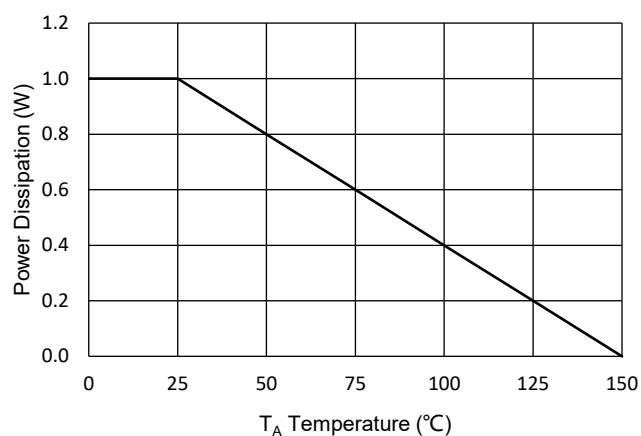


Fig.11 - PD Dissipation



Curve Characteristics

Fig.12 - Safe Operation Area

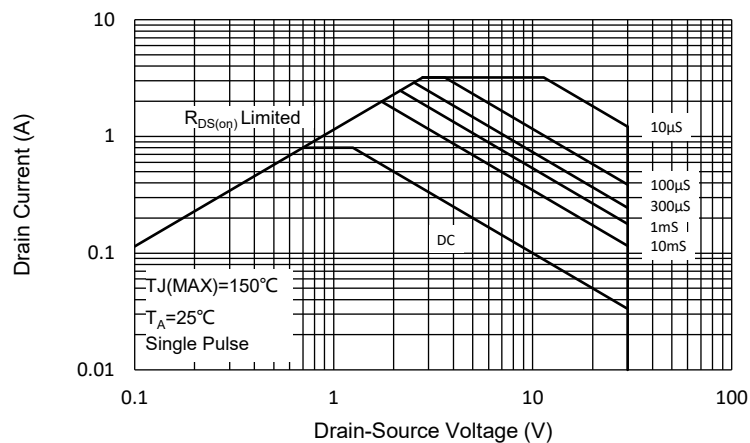
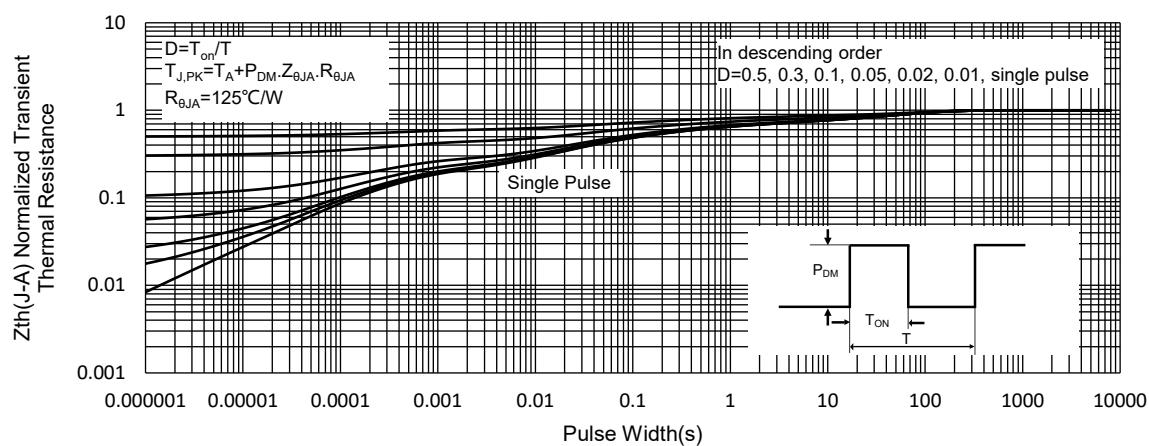


Fig.13 - Normalized Transient Thermal Impedance



Ordering Information

Device	Packing
Part Number-TP	Tape&Reel:3Kpcs/Reel

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